



INTEGRATED SILICON SOLUTION, INC.

## Process Change Notification

**Date:** June 5, 2018

**Change Notification No.** PCN2018-0009

**From:** ISSI-Integrated Silicon Solution, Inc.

### ISSI Part Number Change:

**Old Part Number**

IS62WV1288DALL-xxxx

IS62WV1288DBLL-xxxx

IS65WV1288DBLL-xxxx

**New Part Number**

IS62WV1288FALL-xxxx

IS62WV1288FBLL-xxxx

IS65WV1288FBLL-xxxx

**Description of the Change:** This is to introduce a new die of 1Mbit low power SRAM, 128Kx8, based on 65 nm technology that is a form, fit, and function equivalent.

**Reason for the Change:** Die shrink of current 130nm die from Globalfoundries to 65nm die from SMIC Beijing. This is to ensure product long term support and provide product performance improvement.

### Schedule:

**Sample Date:**

Available Now

**Characterization Data:**

Available Now

**Qualification Data:**

Available Now

**Proposed Effective Date:**

April 1, 2019

**Old Part Number Last Order Date:**

December 17, 2018

**Old Part Number Last Ship Date:**

March 31, 2019

Please contact marketing at [sram@issi.com](mailto:sram@issi.com) for further information.

**Old part number****New part number**

IS62WV1288DALL-55BLI	IS62WV1288FALL-55BLI
IS62WV1288DBLL-45HLI	IS62WV1288FBLL-45HLI
IS62WV1288DBLL-45HLI-TR	IS62WV1288FBLL-45HLI-TR
IS62WV1288DBLL-45QLI	IS62WV1288FBLL-45QLI
IS62WV1288DBLL-45QLI-TR	IS62WV1288FBLL-45QLI-TR
IS62WV1288DBLL-45TLI	IS62WV1288FBLL-45TLI
IS62WV1288DBLL-45TLI-TR	IS62WV1288FBLL-45TLI-TR
IS65WV1288DBLL-45HLA3	IS65WV1288FBLL-45HLA3
IS65WV1288DBLL-45TLA3	IS65WV1288FBLL-45TLA3
IS65WV1288DBLL-45TLA3-TR	IS65WV1288FBLL-45TLA3-TR